

Title (en)
LIGHT-EMITTING DIODE PACKAGE

Title (de)
LICHTEMITTIERENDES DIODENPAKET

Title (fr)
BOÎTIER DE DIODE ÉLECTROLUMINESCENTE

Publication
EP 3806173 A4 20220302 (EN)

Application
EP 19820318 A 20190611

Priority
• KR 20180067055 A 20180611
• KR 2019006996 W 20190611

Abstract (en)
[origin: EP3806173A1] Disclosed is a light emitting diode package. The light emitting diode package includes: a light emitting diode chip provided at a lower side thereof with a first electrode pad and a second electrode pad; a first lead and a second lead spaced apart from each other and contacting the first electrode pad and the second electrode pad of the light emitting diode chip to be electrically connected thereto, respectively; and a housing formed to surround the first lead and the second lead and having a cavity open at a top portion thereof. The first lead and the second lead have a first lead exposing plane and a second lead exposing plane disposed on a bottom surface of the cavity of the housing and partially exposing the first lead and the second lead, respectively. The first lead exposing plane and the second lead exposing plane may be formed in sizes and shapes corresponding to the first electrode pad and the second electrode pad, respectively.

IPC 8 full level
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CPC (source: CN EP KR US)
H01L 33/20 (2013.01 - KR); **H01L 33/38** (2013.01 - EP KR US); **H01L 33/48** (2013.01 - CN); **H01L 33/483** (2013.01 - KR); **H01L 33/486** (2013.01 - EP US); **H01L 33/62** (2013.01 - CN EP KR US); **H01L 25/167** (2013.01 - EP)

Citation (search report)
• [X] EP 2950358 A2 20151202 - LG INNOTEK CO LTD [KR]
• [X] KR 20160057146 A 20160523 - LG INNOTEK CO LTD [KR]
• [X] WO 2015092781 A1 20150625 - KONINKL PHILIPS NV [NL]
• [X] JP 2012182215 A 20120920 - NICHIA KAGAKU KOGYO KK
• [X] WO 2014184698 A1 20141120 - KONINKL PHILIPS NV [NL]
• [X] KR 20140089896 A 20140716 - LG INNOTEK CO LTD [KR]
• [A] US 2013001632 A1 20130103 - IMAI NOBORU [JP], et al
• See references of WO 2019240461A1

Designated contracting state (EPC)
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